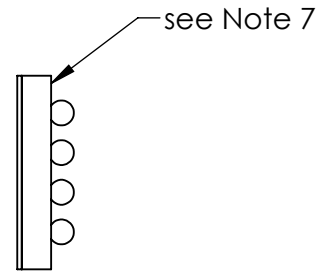
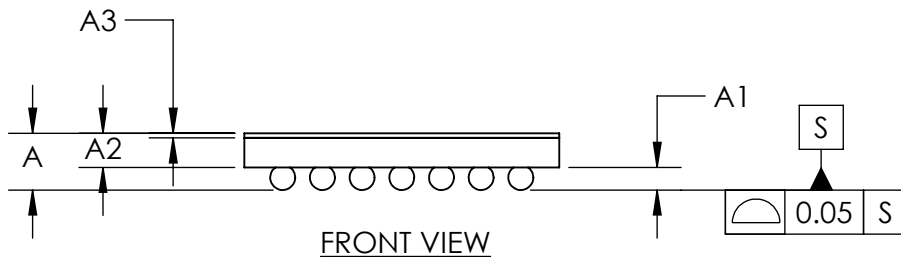


TOP VIEW

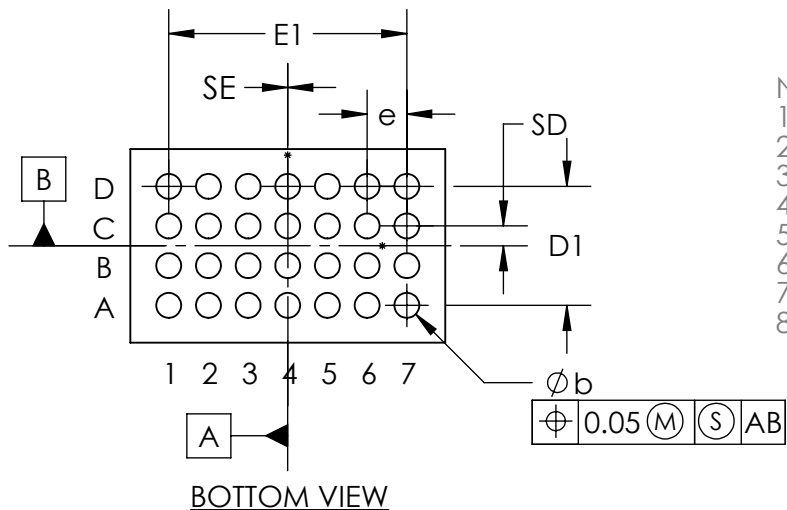


SIDE VIEW

COMMON DIMENSIONS	
A	0.50 MAX
A1	0.17 ±0.03
A2	0.30 REF
A3	0.04* BASIC
b	∅0.22 ±0.03
D	1.708 ±0.025
E	2.778 ±0.025
D1	1.05 BASIC
E1	2.10 BASIC
e	0.35 BASIC
SD	0.175 BASIC
SE	0.00 BASIC
DEPOPULATED BUMPS: NONE	



FRONT VIEW




BOTTOM VIEW

NOTES:

1. Terminal pitch is defined by terminal center to center value.
2. Outer dimension is defined by center lines between scribe lines.
3. All dimensions in millimeter.
4. Marking shown is for package orientation reference only.
5. Tolerance is ± 0.02 unless specified otherwise.
6. All dimensions apply to PbFree (+) package codes only.
7. Front - side finish can be either Black or Clear.
8. *For 12" wafer, A3 = 0.025mm.

- DRAWING NOT TO SCALE -

			
TITLE			
PACKAGE OUTLINE 28 BUMPS THIN WLP PKG. 0.35 mm PITCH,N281A2+1			
APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-100259	C	1/1